





NPN SILICON PLANAR EPITAXIAL DARLINGTON TRANSISTORS

MPSA28 / MPSA29





ABSOLUTE MAXIMUM RATINGS

DESCRIPTION	SYMBOL	MPSA28	MPSA29	UNITS	
Collector Emitter Voltage	V _{CES}	80	100	V	
Collector Base Voltage	V _{CBO}	80	100	V	
Emitter Base Voltage	V _{EBO}	12	V		
Collector Current Continuous	I _C	500	mA		
Power Dissipation at T _a =25°C	P _D	625			
Derate Above 25°C		5.0			
Power Dissipation at T _c =25°C	P _D	1.5	W		
Derate Above 25°C		12	mW/ºC		
Operating And Storage Junction Temperature Range	T_j , T_{stg}	- 55 to +150			

THERMAL CHARACTERISTICS

Junction to Ambient in free air	$R_{th (j-a)}$	200	°C/W
Junction to Case	R _{th (j-c)}	83.3	°C/W

ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

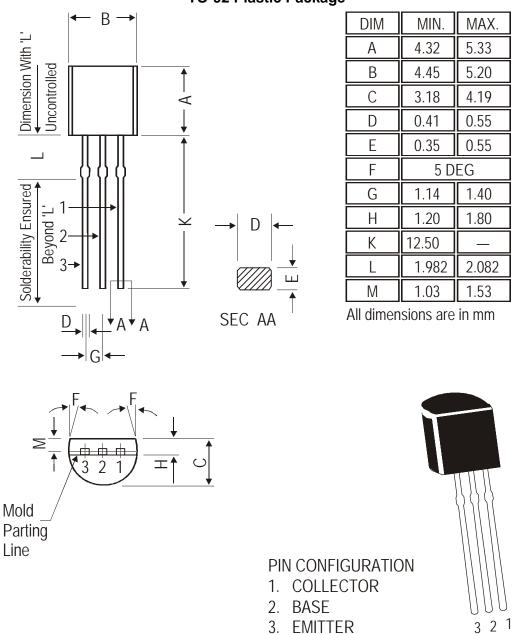
DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
Collector Emitter Voltage	V_{CES}	$I_C = 100 \mu A, V_{BE} = 0$			
		MPSA28	80		V
		MPSA29	100		V
Collector Base Voltage	V_{CBO}	$I_{C}=100\mu A,\ I_{E}=0$			
		MPSA28	80		V
		MPSA29	100		V
Emitter Base Voltage	V_{EBO}	$I_{E}=10\mu A,\ I_{C}=0$	12		V
Collector Cut Off Current	I _{CBO}	V_{CB} =60V, I_{E} =0, MPSA28		100	nA
		V_{CB} =80V, I_E =0, MPSA29		100	nA
Collector Cut Off Current	I _{CES}	V_{CE} =60V, V_{BE} =0, MPSA28		500	nA
		$V_{CE}=80V$, $V_{BE}=0$, MPSA29		500	nA
Emitter Cut Off Current	I _{EBO}	$V_{EB} = 10V, I_C = 0$		100	nA
DC Current Gain	*h _{FE}	$V_{CE}=5V, I_{C}=10mA$	10,000		
		V_{CE} =5V, I_{C} =100mA	10,000		
Collector Emitter Saturation Voltage	*V _{CE (sat)}	$I_C=10$ mA, $I_B=0.01$ mA		1.2	V
		$I_C=100$ mA, $I_B=0.1$ mA		1.5	V
Base Emitter On Voltage	*V _{BE (on)}	V_{CE} =5V, I_{C} =100mA		2.0	V
Current Gain Bandwidth Product	**f _T	I _C =10mA, V _{CE} =5V, f=100MHz	125		MHz
Output Capacitance	C_{ob}	V _{CB} =10V, I _E =0V, f=1.0 MHz		8.0	pF

^{*}Pulse test: Pulse Width <300ms, Duty Cycle<2%

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^{**} $f_T = Ih_{fe}I^* f_{test}$

TO-92 Plastic Package



The TO-92 Package, Tape and Ammo Pack Drawings are correct as on the date of issue/revision of this Data Sheet.

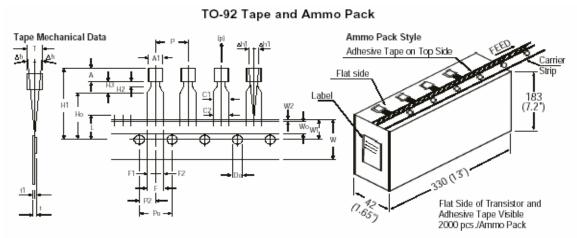
The currently valid dimensions and information, may please be confirmed from the TO-92 Drawing in the Packages and Packing Section of the Product Catalogue.

Packing Details

PACKAGE	STANDARD PACK		INNER CARTON BOX		OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	GrWt
TO-92 Bulk	1K/polybag	200 gm/1 K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

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TO-92 Plastic Package



All dimensions are in mm

		SPECIFICATION]
ITEM	SYMBOL	MIN.	NOM.	MAX.	TOL.	
BODY WIDTH	A1	4.45		5.20		ŊO
BODY HEIGHT	Α	4.32		5.33		1. 1
BODY THICKNESS	T	3.18		4.19		1
PITCH OF COMPONENT	Р		12.7		± 1.0	2. 1
*1FEED HOLE PITCH	Po		12.7		± 0.3	_ i
*2 FEED HOLE CENTRE TO COMPONENT CENTRE	P.0					'
	P2		6.35		± 0.4	3.
DISTANCE BETWEEN OUTER LEADS	F		5.08		+ 0.6 - 0.2	1
*3 COMPONENT ALIGNMENT SIDE VIEW	Δh		0	1.0		4.
*4 COMPONENT ALIGNMENT FRONT VIEW	∆h1		0	1.3		
TAPE WIDTH	w		18		± 0.5	'
HOLD-DOWN TAPE WIDTH	Wo		6		± 0.2	5. /
HOLE POSITION	W1		9		+ 0.7	
					- 0.5	6.
HOLD-DOWN TAPE POSITION	W2	0.0	١	0.7		0. ;
LEAD WIRE CLINCH HEIGHT	Ho		16		± 0.5	'
COMPONENT HEIGHT	H1			24.0		
LENGTH OF SNIPPED LEADS	L		١.	11.0		
FEED HOLE DIAMETER	Do		4	1.2	± 0.2	RE
*5 TOTAL TAPE THICKNESS LEAD - TO - LEAD DISTANCE	t	2.40		1.2		*1
LEAD - TO - LEAD DISTANCE	F1, F2	2.40		2.70	- 0.1	*2
STAND OFF	H2	0.45		1.45		*3
CLINCH HEIGHT	H3			3.0		l
LEAD PARALLELISM	C1 - C2			0.22		*4
PULL - OUT FORCE	(p)	6N				*5

NOTES

- Maximum alignment deviation between leads will not to be greater than 0.2mm.
- Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.
- Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.
- There will be no more than three (3) consecutive missing components in a tape.
- A tape trailer, having at least three feed holes are provided after the last component in a tape.
- Splices should not interfere with the sprocket feed holes.

REMARKS

- *1 Cumulative pitch error 1.0 mm/20 pitch
- *2 To be measured at bottom of clinch
- *3 At top of body
- *4 At top of body
- *5 t1 0.3 0.6 mm

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

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Customer Notes MPSA28 / MPSA29

TO-92 Plastic Package

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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